

Sub 17  
B1

attaching an interposer to a package substrate;  
attaching an integrated circuit die to the interposer, wherein the integrated circuit die includes an active region;  
covering the package substrate, the integrated circuit die, and the interposer with a heat spreader to form an internal chamber;  
filling the internal chamber with a cooling fluid, wherein the cooling fluid contacts a region between the interposer and the integrated circuit die and wherein the cooling fluid contacts the active region.

- Sub 17  
B2
17. (Amended) An integrated circuit package comprising:  
a package substrate;  
a first integrated circuit die having an active surface;  
an interposer disposed between the package substrate and the first integrated circuit die, the interposer establishing electrical connectivity between the first integrated circuit die and the package substrate; and  
a cooling fluid disposed between the first integrated circuit die and the interposer, wherein the cooling fluid contacts the active surface.